

2812

AUG 26 2002

**STATEMENT UNDER 37 CFR 1.97(e) ACCOMPANYING
INFORMATION DISCLOSURE STATEMENT**

In Re Application Of: Ray et al.

Docket No.
END920010002US111 / IDS
e. willis
9 - 10 - 02

Serial No.	Filing Date	Examiner	Group Art Unit
09/779,812	2/8/01	Nguyen, Ha T.	2812

Invention: **LEAD-FREE SOLDER STRUCTURE AND METHOD FOR HIGH FATIGUE LIFE**

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TO THE ASSISTANT COMMISSIONER FOR PATENTS:

This is a statement under the provisions of 37 CFR 1.97(e) in the above-identified application.

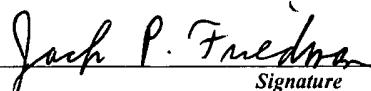
Check applicable statement herebelow:

Statement Under 37 CFR 1.97(e)(1)

- Each item of information contained in the accompanying Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the Information Disclosure Statement.

Statement Under 37 CFR 1.97(e)(2)

- No item of information contained in the accompanying Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the undersigned person, after making reasonable inquiry, no item of information contained in the accompanying Information Disclosure Statement was known to any individual designated in 37 CFR 1.56(c) more than three months prior to the filing of the Information Disclosure Statement.


Jack P. Friedman
Signature

Dated: 8/21/02

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